



TSMC Board of Directors Meeting Resolutions

HSINCHU, Taiwan, R.O.C., Aug. 12, 2025 – The TSMC (TWSE: 2330, NYSE: TSM) Board of Directors today held a meeting, which passed the following resolutions:

1. Approved the 2025 second quarter Business Report and Financial Statements. Second quarter consolidated revenue was NT\$933.79 billion, and net income was NT\$398.27 billion, with diluted earnings per share of NT\$15.36.
2. Approved the distribution of a NT\$5.0 per share cash dividend for the second quarter of 2025, and set December 17, 2025 as the record date for common stock shareholders entitled to participate in this cash dividend distribution, and the ex-dividend date for the common shares shall be December 11, 2025. As required by Article 165 of Taiwan's Company Law, the shareholders' register shall be closed for five days prior to the record date (December 13 through December 17, 2025) for registration transfer, and the dividend will be paid on January 8, 2026. In addition, the ex-dividend date and the record date for entitlement to participate in this cash dividend distribution for TSMC American Depositary Shares (ADSs) will be December 11, 2025.
3. To meet long-term capacity plans based on market demand forecasts and TSMC's technology development roadmap, the Board approved capital appropriations of approximately US\$20,657.50 million for purposes including: 1) Installation of advanced technology capacity; 2) Installation of advanced packaging, mature and/or specialty technology capacity; 3) Fab construction, and installation of fab facility systems.
4. Approved the issuance of unsecured corporate bonds in multiple offerings in the domestic market in an amount not to exceed NT\$60 billion to finance TSMC's capacity expansion and/or green initiatives.
5. Approved the capital injection of not more than US\$10 billion to TSMC Global, a wholly-owned subsidiary of TSMC, for the purpose of reducing foreign exchange hedging costs.



About TSMC

TSMC pioneered the pure-play foundry business model when it was founded in 1987 and has been the world's leading dedicated semiconductor foundry ever since. The Company supports a thriving ecosystem of global customers and partners with the industry's leading process technologies and portfolio of design enablement solutions to unleash innovation for the global semiconductor industry. With global operations spanning Asia, Europe, and North America, TSMC serves as a committed corporate citizen around the world.

TSMC deployed 288 distinct process technologies, and manufactured 11,878 products for 522 customers in 2024 by providing the broadest range of advanced, specialty and advanced packaging technology services. The Company is headquartered in Hsinchu, Taiwan. For more information please visit <https://www.tsmc.com>.

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